Product / Process Change Notification



N° 2020-170-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an additional assembly and final test location at Huayi Microelectronics Co., Ltd (HYME) for Coolmos[™], package TO220

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 16. March 2021.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Dr. Wolfgang Eder Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider Registered Office: Neubiberg Commercial Register: München HRB 126492

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► **Products affected:** AS per attached list with affected products 1_cip20170_a

Detailed Change Information:

Subject:	Introduction of an additional assembly and final test location at Huayi Microelectronics Co., Ltd (HYME) for Coolmos [™] , package TO220	
Reason:	Expansion of Assembly and test location to assure continuity and increase supply flexibility.	
Description:	<u>Old</u>	New
	ASE (Weihai) Inc., China	ASE (Weihai) Inc., China
	Infineon Technologies (Malaysia) Sdn. Bhd	Infineon Technologies (Malaysia) Sdn. Bhd
		Huayi Microelectronics Co., Ltd (HYME) in Xi'An,
Product Identification:	entification: Traceability via Baunumber, Lotnumber, date code & Marking (refer to attached 3_cip20170_a)	
Impact of Change:	 NO change on electrical and thermal performance NO impact on the device reliability as proven via product qualification. NO impact on the electrical parameters and device processability at customer end. The package outer dimensions remain unchanged. Product datasheet remain unchanged. 	
Attachments:	Affected product list: 1_cip20170_aQualification Test Report: 2_cip20170_aCustomer Info Package: 3_cip20170_a	
Time Schedule:		
Final qualification report:	available	
 First samples available: 	on request	
Intended start of delivery:	May 2021 onward, depending on customer's approval	

If you have any questions, please do not hesitate to contact your local Sales office.